



Product Change Notification: MAAN-05PFQZ171

Date:

13-May-2026

Product Category:

Gate Drivers and Motor Drivers

Notification Subject:

CCB 7927 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MTD6508-ADJE/JQ and MTD6508T-ADJE/JQ catalog part numbers (CPN) available in 16L UQFN 4x4x0.5mm) package at MMT assembly site.

Affected CPNs:

[MAAN-05PFQZ171_Affected_CPN_05132026.pdf](#)

[MAAN-05PFQZ171_Affected_CPN_05132026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MTD6508-ADJE/JQ and MTD6508T-ADJE/JQ catalog part numbers (CPN) available in 16L UQFN 4x4x0.5mm) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519	QMI519	No

Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	EFTEC-64T	EFTEC-64T	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 15 June 2026 (date code: 2625)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	January 2026					>	May 2026					June 2026				
Work Week	01	02	03	04	05		18	19	20	21	22	23	24	25	26	27
Initial PCN Issue Date		X														
Qual Report Availability									X							
Final PCN Issue Date									X							
Estimated Implementation Date														X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: January 06, 2026: Issued initial notification.

May 13, 2026: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 15, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance

regarding the material content of the applicable product.

Attachments:

[PCN_MAAN-05PFQZ171_Qualification Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

MTD6508-ADJE/JQ

MTD6508T-ADJE/JQ



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QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: MAAN-05PFQZ171

Date:
May 5, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MTD6508-ADJE/JQ and MTD6508T-ADJE/JQ catalog part numbers (CPN) available in 16L UQFN 4x4x0.5mm) package at MMT assembly site.



MICROCHIP Package Qualification Report

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MTD6508-ADJE/JQ and MTD6508T-ADJE/JQ catalog part numbers (CPN) available in 16L UQFN 4x4x0.5mm) package at MMT assembly site.

CCB No. 7927

Misc.	Assembly site	MMT
	BD Number	BD-003741-01
	MP Code (MPC)	UGBC14JQXA00
	Part Number (CPN)	MTD6508-ADJE/JQ
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	91
Lead-Frame	Paddle size	110x110
	Material	EFTEC-64T
	DAP Surface Prep	Bare Cu
	Treatment	Roughening LF
	Process	Etched
	Lead-lock	Yes
	Part Number	10101611
	Lead Plating	Matte Tin
	Strip Size	250x70mm
	Strip Density	700 unit/strip
Bond Wire	Material	CuPdAu
Die Attach	Part Number	QMI519
	Conductive	Yes
MC	Part Number	G700LTD
PKG	PKG Type	UQFN
	Pin/Ball Count	16
	PKG width/size	4x4x0.5mm



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Package Qualification Report

Manufacturing Information:

Assembly Lot No.
MMT-263500781.000
MMT-263500917.000
MMT-263600050.000

Conclusion:

Qualification of UGBC1 mask / MTD6508T-ADJE/JQ product / 0.8 mil CuPdAu wire in 16L UQFN 4x4x0.5mm (JQX) package at MMT site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	R2600043-1 MMT-263500781.000	R2600043-2 MMT-263500917.000	R2600043-3 MMT-264200095.000
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: ETS88	25°C and 125°C		
Result	Passed		

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 500 hours		
Required Sample Size	45 units each lot / 3 lots; WBP/WBS		
Lot ID	R2600043-1 MMT-263500781.000	R2600043-2 MMT-263500917.000	R2600043-3 MMT-264200095.000
Electrical Results (Fail / Pass)	0/45	0/45	0/45
WBS (Fail / Pass)	0/3	0/3	0/3
WBP (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: ETS88	25°C and 125°C		
Result	Passed		

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-55°C / +150°C Air to Air / 1000 Cycles		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS		
Lot ID	R2600043-1 MMT-263500781.000	R2600043-2 MMT-263500917.000	R2600043-3 MMT-264200095.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: ETS88	25°C and 125°C		
Result	Passed		

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 96 hours / Bias Voltage: 5.5V		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS		
Lot ID	R2600043-1 MMT-263500781.000	R2600043-2 MMT-263500917.000	R2600043-3 MMT-264200095.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: ETS88	25°C and 125°C		
Result	Passed		

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600043-1 MMT-263500781.000	R2600043-2 MMT-263500917.000	R2600043-3 MMT-264200095.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: ETS88	25°C		
Result	Passed		

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22 - Passed

Physical Dimension (0Hr)

Test Method	JESD22 B100 and B108
Test Criteria	Within package diagram dimension
Required Sample Size	10 units each lot / 3 lots
Result (Fail / Pass)	0/30 - Passed

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 - Passed

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 – Passed